

LINEAR TECHNOLOGY MATERIALS DECLARATION

LTC2348ILX-18#PBF

(Engineering Calculation)

LQFP 7mm X 7mm

(printed on: 2017-12-03 11:57:36)

TOTAL MASS
(g): **0.193382**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.003709	1000000	19179.625		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.042592	693000	220247.671875		
		Iron (Fe)	7439-89-6	0.000651	10599.9990234	3366.38891602		
		Phosphorus (P)	7723-14-0	0.000000	0	0		
		Zinc (Zn)	7440-66-6	0.000602	9800	3113.00463867		
		Nickel (Ni)	7440-02-0	0.013288	216200.015625	68713.6328125		
		Silicon (Si)	7440-21-3	0.000037	600	191.330871582		
		Magnesium (Mg)	7439-95-4	0.001561	25400	8072.09423828		
		Tin (Sn)	7440-31-5	0.002397	39000	12395.1367188		
		Lead Frame Total:				0.061128	994600	316099.25
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.002712	1000000	14025.5625		
		External Plating Total:				0.002712	1000000	14025.5625
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001274	1000000	6587.98681641		
		Internal Plating Total:				0.001274	1000000	6587.98681641
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001111	750000	5745.09667969		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000370	250000	1913.30847168		
		Die Attach Total:				0.001481	1000000	7658.40527344
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.012573	103000	65016.2929688		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.109253	895000	564958.625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		

		Carbon Black (C)	1333-86-4	0.000244	2000	1261.74938965
		Encapsulation Total:		0.122070	1000000	631236.6875
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.001008	1000000	5212.47314453
TOTAL MASS (g):						0.193382